

(Amended)

~~53~~

C A ceramic/metal substrate, comprising a ceramic layer forming at least two substrate areas connected to each other as one piece and joined to each other on at least one predetermined break line provided for in the ceramic layer, metal surfaces on at least one side of the ceramic layer, said metal surfaces being provided on said substrate areas such, that the metal surfaces on neighbored substrate areas are at a distance from the predetermined break line and from one another along said at least one breaking line, said metal surfaces being formed by a metalization which had been bonded to the ceramic layer by a heat process elected from the group consisting of direct bonding or active soldering and by structuring the metalization after bonding, that at least one metal surface of each substrate areas has an edge reduction on an edge region adjacent to the predetermined break line and running along this predetermined break line, the edge reduction being of a form that the mass of metal there per volume (specific metal mass) is reduced 10 - 80% along the edge region with reference to the specific metal mass of metal surface outside the edge reduction.

(New)

~~54~~

C2 A ceramic/metal substrate, comprising a ceramic layer forming at least two substrate areas connected to each other as one piece and joined to each other on at least one predetermined break line provided for in the ceramic layer, metal surfaces on at least one side of the ceramic layer, said metal surfaces being provided on said substrate areas such, that the metal surfaces on neighbored substrate areas are at a distance from the predetermined break line and from one another along said at least one breaking line, said metal surfaces being formed by a metalization which had been

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but

bonded to the ceramic layer by a heat process elected from the group consisting of direct bonding or active soldering and by structuring the metalization after bonding, that at least one metal surface of each substrate areas has an edge reduction on an edge region adjacent to the predetermined break line and running along this predetermined break line, the edge reduction being of a form that the mass of metal there per volume (specific metal mass) is reduced 10 - 80% along the edge region with reference to the specific metal mass of metal surface outside the edge reduction,

said edge reduction being formed by depressions, hollows, grooves or steps in the material of the metal surface.

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(Amended) 53. A ceramic/metal substrate, comprising a ceramic layer forming at least two substrate areas connected to each other as one piece and [joining] joined to each other on at least one predetermined break line provided for in the ceramic layer,  
metal surfaces on at least one side of the ceramic layer, said metal surfaces being provided on said substrate areas such, that the metal surfaces on neighbored substrate areas are at a distance from the predetermined break line and from one another along said at least one breaking line,  
said metal surfaces being formed by a metalization which had been bonded to the ceramic layer by a heat process elected from the group consisting of direct bonding or active soldering and by structuring the metalization after bonding,  
that at least one metal surface of each substrate areas has an edge reduction on an edge region adjacent to the predetermined break line and running along this predetermined break line,  
the edge reduction being of a form that the mass of metal there per volume (specific metal mass) is reduced 10 - 80% along the edge region with reference to the specific metal mass of metal surface outside the edge reduction.

